

**In the Specification**

**Amend the paragraph beginning at page 9 line 1 as follows:**

Energy can also be applied to the substrate or substrate support directly to dislodge the particles. Energy means such as a vibrator can be used to vibrate the substrate and dislodge the particles. Centrifugal means can also be used to dislodge the particles. Other means include magnetic forces, thermal means, lasers, ~~electrostatic etc~~electrostatic, etc. Gravity forces may also be used with an inclined substrate as discussed above and as shown in Figs. 3A-3C.

**Amend the paragraph beginning at page 10 line 14 as follows:**

Accordingly, Fig. 2A shows a semiconductor wafer electronic component generally as numeral 10 which comprises a wafer substrate 11 having contaminate particulate matter 12 on the surface thereof. The substrate is supported on base 16. In Fig. 2B, an energy force is shown as 17 which is directed at the ~~substrate~~base 16 and may be, for example, a vibrational energy source, a centrifugal energy force, or the like. The purpose of the energy source 17 is to dislodge the particles 12 from the surface of substrate 11 so that they are partially or totally encapsulated in coating 13 as shown in Fig. 2C.